PCN Number: 202310040			03.1A				PCN Date:		December (2023	07,
Title: Qualification of alternate lead finish material for select devices										
Custom	er Conta	ct:	Change Management team Dept				:	Qua	lity Services	,
Proposed 1 st Ship Date:			Jan 3, 2024 Sample I				Requests ted until:		Dec 30, 2023*	
*Sample	*Sample requests received after Dec 30, 2023 will not be supported. (Rev A Devices only)									
Change	Type:									
Asse	embly Site	e		Design			Wat	Wafer Bump Material		
	embly Pro			Data Sheet					Process	
	embly Ma			Part number change			_	Wafer Fab Site Wafer Fab Material		
		pecification	.	☐ Test Site ☐ Test Process ☐			Wafer Fab Material Wafer Fab Process			
L Paci	Kiriy/Sirip	ping/Labeling		PCN De			_ wai	iei rab	Process	
Descrin	tion of C	hanger		PCN DE	Lalis					
Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for the newly added devices only. This PCN is to inform of an alternate lead finish material set for the list of devices in the product affected sections below.										
	W	hat		Current			Additional			
		finish		NiPd <i>A</i>			Matte Sn			_
	LCau	11111311		NIPUF	\u			маше	311	
Qualification results are shown below										
Reason	for Chan	ige:								
Standardization										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):										
None										
Impact on Environmental Ratings										
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.										
				ACH Green Status					C 62474	
⊠ No C	Change	🖾 r	No Change		⊠ No Change		⊠ No Ch		hange	
Changes to product identification resulting from this PCN:										
None										
Product	Affected	d:								
			259461LF	RPWR TPS	TPS259851RQPR			TPS25990ARQPR		

SN611782BRQER



TI Information Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS53831RWZR	Qual Device: TPS543620RPYR	Qual Device: TPS62903RPJR	QBS Package Reference: <u>SN62825DMQR</u>	QBS Package Reference: <u>TPS62085RLTR</u>
AC	Autoclave 121C	96 Hours	3/231/0	-	3/231/0	-	3/231/0
CDM	ESD - CDM	1500V	-	-	-	2/6/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	2/154/0	-	-	3/231/0	3/231/0
HBM	ESD - HBM	3000V	-	-	-	1/3/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	3/2310
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0	3/231/0	3/231/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass
MSL	Thermal Integrity Sequence	Level 2-260C	3/36/0	3/36/0	3/36/0	-	3/36/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	3/15/0	3/15/0	-	3/15/0
SD	Solderability	Pb Free	3/66/0	3/66/0	3/66/0	2/44/0	3/66/0
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	3/231/0	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	-
VM	Visual Quality Reliability Inspection	Post Temp Cycle	3/6/0	3/6/0	3/6/0	-	3/6/0

⁻ QBS: Qual By Similarity

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20210118-137850

Rev A Device qual memo

⁻ QBS: Qual By Similanty
- Qual Device TPS53831RWZR, TPS543620RPYR, TPS62903RPJR are qualified at LEVEL2-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

⁻ The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Qualification Report

CDAT Hotrod Bare Cu LF + Post mold plating qualification + G700LTD-S(CF) Approve Date 26-October-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>SN611781BRQER</u>	Qual Device: <u>TPS259461LRPWR</u>
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0
SD	СЗ	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	3/66/0	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/15/0	3/15/0

- · QBS: Qual By Similarity
- Qual Device SN611781BRQER is qualified at MSL2 260C
- Qual Device TPS259461LRPWR is qualified at MSL2 260C
- · Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2210-013

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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